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Uhland et al.

(54) SYSTEMS AND METHODS FOR HIGH DENSITY MULTI-COMPONENT MODULES

(75) Inventors: **Scott A. Uhland**, Redwood City, CA (US); **Seth M. Davis**, Lexington, MA (US); **Stanley R. Shanfield**, Newton, MA (US); **Douglas W. White**, Lexington, MA (US); **Livia M. Racz**, Belmont, MA (US)

Correspondence Address:
FISH & NEAVE IP GROUP
ROPES & GRAY LLP
ONE INTERNATIONAL PLACE
BOSTON, MA 02110-2624

(73) Assignee: **The Charles Stark Draper Laboratory, Inc.**, Cambridge, MA (US)

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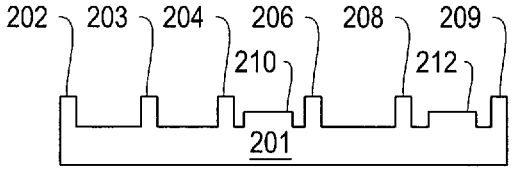
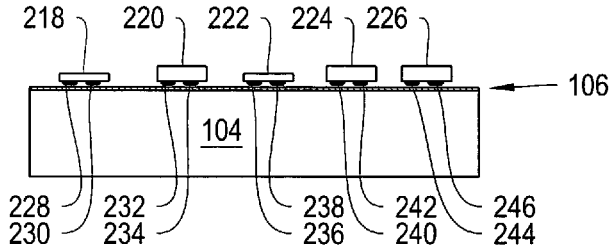
(57) **ABSTRACT**

A method for forming a device, comprising providing a first substrate carrying a first set of components disposed in a first encapsulating layer over the first set of components, providing a second substrate carrying a second set of components disposed in a second encapsulating layer over the second set of components, bonding the first and second substrates and functionally interconnecting at least one of the predefined components in the first set of components with at least one of the components in the second set of components.